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**INFORMATION DISCLOSURE  
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Sheet **3** of

**Complete if Known**

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| Application Number     | 09/854,083         |
| Filing Date            | May 11, 2001       |
| First Named Inventor   | Tan, Zhengquan     |
| Art Unit               | 2823               |
| Examiner Name          | William D. Coleman |
| Attorney Docket Number | A5771/T42200       |

**U.S. PATENT DOCUMENTS**

| Examiner | Cite No. <sup>1</sup> | Document Number<br>Number Kind Code <sup>2</sup> (if known) | Publication Date<br>MM-DD-YYYY | Name of Patentee or<br>Applicant of Cited Document | Pages, Columns, Lines, Where<br>Relevant Passages or Relevant<br>Figures Appear |
|----------|-----------------------|---|--------------------------------|--|---|
|          | AA                    | 6,030,881   | 02-29-2000                     | Papasoulitis et al.                                |   |
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**FOREIGN PATENT DOCUMENTS**

| Examiner<br>Initials* | Cite<br>No. <sup>1</sup> | Foreign Patent Document<br>Country Code <sup>3</sup> Number <sup>4</sup> Kind Code <sup>5</sup> (if known) | Publication Date<br>MM-DD-YYYY | Name of Patentee or<br>Applicant of Cited<br>Document | Pages, Columns, Lines,<br>Where Relevant<br>Passages or Relevant<br>Figures Appear | T <sup>6</sup> |
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**OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS**

| Examiner<br>Initials* | Cite<br>No. <sup>1</sup> | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the<br>item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue<br>number(s), publisher, city and/or country where published. | T <sup>2</sup> |
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|                       | AB                       | G.Y. LEE et al., "A Low Redeposition Rate High Density Plasma CVD Process for High Aspect Ratio 175 mm<br>Technology and Beyond," <i>Proceedings of IEEE 1999 International Interconnect Technology Conference</i> , pp. 152-154<br>(1999).                           |                |
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| Examiner<br>Signature |  | Date<br>Considered | 10/12/02 |
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